

**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	MDG/20/12191	
<b>1.3 Title of PCN</b>	ASE Kaohsiung (Taiwan) additional source and Product enhancement for STM32MP15x in LFBGA18X18 package source	
<b>1.4 Product Category</b>	LFBGA18X18 for STM32MP15x products	
<b>1.5 Issue date</b>	2020-06-16	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	NEMETH KRISZTINA
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<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Ricardo Antonio DE SA EARP
<b>2.1.2 Marketing Manager</b>	Veronique BARLATIER
<b>2.1.3 Quality Manager</b>	Pascal NARCHE

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	Crolles 300 (France) AMKOR ATK (Korea) ASE KaoHsiung (Taiwan)

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	Product revision B (cut 2.0) Limitations as described in Errata Sheet ES0438 Revision 3 - November 2019 "STM32MP151x STM32MP153x STM32MP157x" Summary of Device errata  Package source: - Amkor ATK (Korea)	New Product Revision Z (cut 2.1) - New Errata sheet ES0438 Revision 4 - January 2020 "STM32MP151x STM32MP153x STM32MP157x" Summary of Device errata  Package dynamic warpage improvement - Amkor ATK (Korea) - existing source - ASE Kaohsiung (Taiwan) - Additional source
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	Function enhancement (New die revision from B to Z) Additional Assembly site	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	New Die revision: product enhancement New Assembly Site: Due to the success on the market of STM32 devices, ST Microcontrollers Division decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.
<b>5.2 Customer Benefit</b>	CAPACITY INCREASE

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	Please refer to PCN12191 Additional information attached document.
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2020-09-21
<b>7.2 Intended start of delivery</b>	2020-10-20
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	12191 MDG-MCD-RERMCD2008 -RERMCD2010 -PCN12191-reliability plan.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2020-06-16

**9. Attachments (additional documentations)**

12191 Public product.pdf  
12191 MDG-MCD-RERMCD2008 -RERMCD2010 -PCN12191-reliability plan.pdf  
12191 PCN12191\_Additional information.pdf

**10. Affected parts**

<b>10. 1 Current</b>		<b>10.2 New (if applicable)</b>
<b>10.1.1 Customer Part No</b>	<b>10.1.2 Supplier Part No</b>	<b>10.1.2 Supplier Part No</b>
3051898	STM32MP151AAA3	
3051903	STM32MP153AAA3	
3018578	STM32MP157AAA3	
3262499	STM32MP151CAA3	
	STM32MP153CAA3	
3262507	STM32MP157CAA3	

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